

The ECX-53B SMD is our sub-miniature SMD crystal with 3.2 x 5 mm footprint. This package is ideal for today's compact wireless applications where board space is critical.

FEATURES

- Compact and low profile
- Seam-welded package
- Tape & Reel (1,000 pcs.)
- High frequency fundamental
- PbFree/RoHS Compliant

PART NUMBERING GUIDE "EXAMPLE"

MANUFACTURER	FREQUENCY (16.000 MHz)	LOAD CAPACITANCE*	PACKAGE TYPE**
ECS	160	20	30B

* Load capacitance (xx=xx pF, S=series resonance) **Package Type Examples (30B=ECX-53B)
 Note: See Product Selection Guide for additional options including tighter tolerances or extended temperature range.

OPERATING CONDITIONS/ELECTRICAL CHARACTERISTICS

PARAMETERS	CONDITIONS	MINIMUM	TYPICAL	MAXIMUM	UNITS
FREQUENCY RANGE		10.000		130.000	MHz
CALIBRATION TOLERANCE	@ +25°C			±50*	PPM
FREQUENCY STABILITY ref @25°C	-20 ~ +70°C			±50*	PPM
SHUNT CAPACITANCE				5	pF
LOAD CAPACITANCE	C _L (Customer Specified)	12	16.0 standard	Series	pF
DRIVE LEVEL	DL			100	µW
OPERATING TEMPERATURE	T _{OPR} **	-20		+70	°C
STORAGE TEMPERATURE	T _{STG}	-40		+85	°C
AGING CHARACTERISTICS (Per Year)	@ +25°C ± 3°C per year			±5	PPM

* Tighter specifications are available. **Extended temperature range available.

EQUIVALENT SERIES RESISTANCE / MODE OF OSCILLATION

FREQUENCY RANGE (MHz)	MODE OF OSC	MAX ESR Ω	FREQUENCY RANGE (MHz)	MODE OF OSC	MAX ESR Ω
10.000 ~ 15.999	Fundamental	80	70.000 ~ 130.000	3rd O/T	100
16.000 ~ 19.999	Fundamental	60	120.000 ~ 130.000	5th O/T	160
20.000 ~ 130.000	Fundamental	50			

PACKAGE DIMENSIONS (mm)

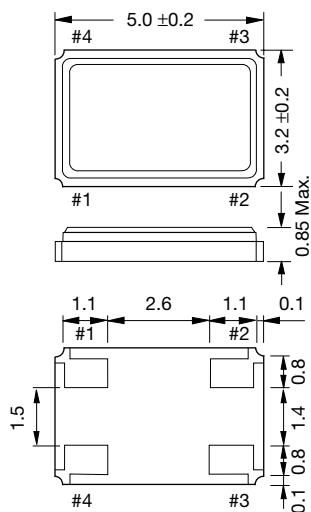


Figure 1) ECX-53B - Top, Side, Bottom and End views

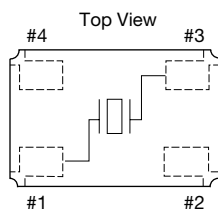
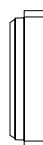


Figure 2) ECX-53B Land Pattern

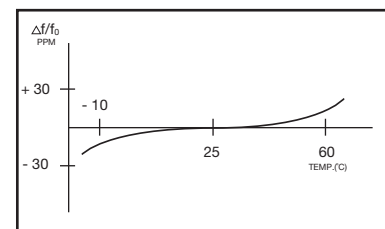


Figure 3) Frequency vs Temperature Curve